



Super SPARC™



A Fully Integrated Superscalar Processor

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Super SPARC™



Program Objectives

Workstation Microprocessor Essentials

- High Performance
- 100% Application Binary Compatible
- High Integration
- Useful in Several Configurations
- Extensive Test/Debug Support

→ SuperSparc Solution

- 3 Instruction Resource-Rich SuperScalar
- Fast Double-Precision Floating Point
- Single Cycle Loads/Stores
- BiCMOS
- SPARC Version 8 Architecture (IMUL/IDIV)
- IU/FPU/MMU/Cache/Mbus on-chip
- All Fully MP "ready"
- Large Internal Caches
- Companion Cache Controller
- Built-in Self Test
- JTAG Scan Based Emulation
- ICE-like debugging features



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Microprocessor



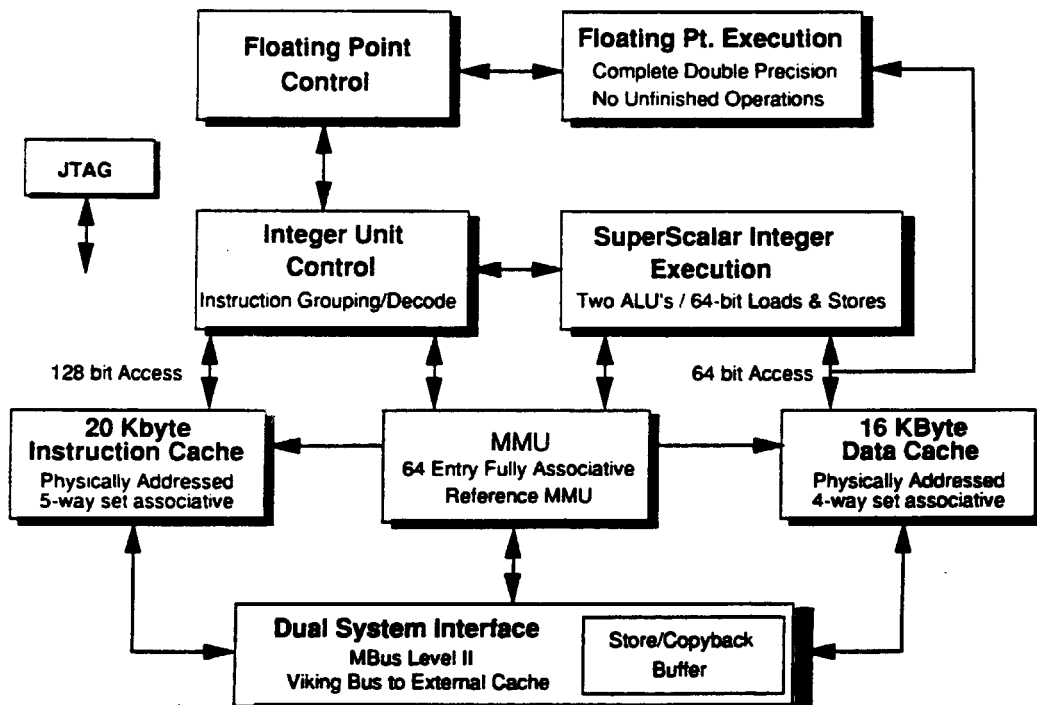
Cache Controller

- High Performance, Superscalar
- Highly Integrated
- 3.1 million transistors, BiCMOS
- 3 Instructions/Cycle Issue and Execution
- SPARC Version 8 Compatible
- Direct MBus Level II or used with External Cache Controller
- Optional External Cache Controller
- Fully integrated, on-board cache tags
- Synch or Async interface to system bus
- 1MB unified, direct-mapped cache
- MBus Level-II Interface
(Cache Consistent Multiprocessor Interconnect)

three



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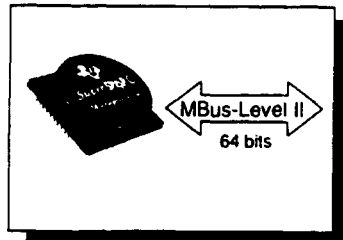


four

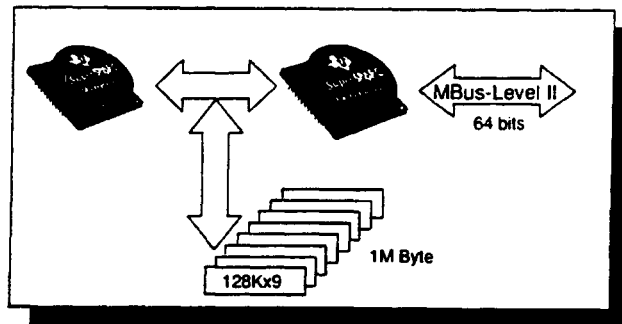


MBus Configurations

Lower Cost Systems



Higher Performance Systems



five



Superscalar Principles of Operation

- 3 instruction/cycle issue & execute, fully dynamic scheduling
- Simultaneous execution may be constrained by:
 - data dependencies
 - control dependencies
 - internal resources
- SuperSPARC Resources:
 - Single 64-bit LD/ST
 - Single Br/Jmp/Call/Return
 - Two 32-bit ALUs
 - Two 32-bit integer results
 - Single FP Issue
- Designed to handle dependencies well, not wish them away

six



Superscalar Example

```

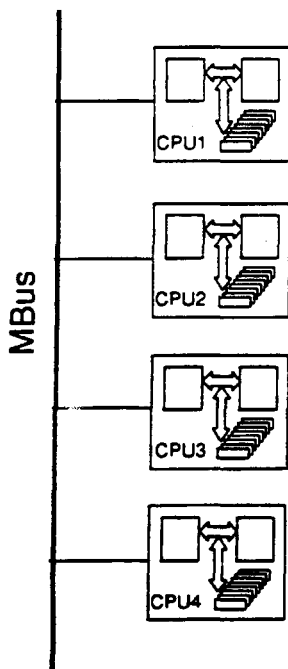
ldd      [%10],%f2
fadd    %f2,%f0,%f6
add     %10,0x8,%10
! -- Break (Three Instructions max)
ldd      [%10],%f4
add     %10,0x4,%10
fmuld   %f4,%f0,%f8
! -- Break (Three Instructions max)
ldd      [%10+4],%f10
cmp     %10,0x100
be      Loop
! -- Break (Branch, Three Instructions)
fadd    %f6,%f8,%f0
.
.

```

size



MBus Multiprocessing



- SuperSPARC has complete multiprocessing support
- First and optional second level caches all coherent
- MBus interface has snoop logic
- Processor not affected by most snoop traffic
- System configuration, memory speed and applications, Limit number of processors that can be supported
- Supports SPARC Architecture Version 8 multiprocessor memory model (Total Store Ordering and Partial Store Ordering)



Super SPARC™



Technology

- SuperSPARC CPU and Cache Controller are manufactured in TI's EPIC IIB process
 - 0.8 micron minimum feature size
 - BiCMOS - Best of Bipolar and CMOS circuits
 - Bipolar: I/O and interconnect
 - CMOS: Density and simplicity
 - Triple Level Metal
- High Performance Dense Ceramic Pin Grid Array (CPGA) with heatsink
 - SuperSPARC CPU: 293 pins, 70 mil pin to pin
 - SuperSPARC CC: 369 pins, 70 mil pin to pin



Super SPARC™



Summary

- 3 instruction Superscalar groups and schedules instructions
- High integration of critical features gives higher performance at lower cost
- BiCMOS for the right balance of speed, density and simplicity
- MBus "multiprocessing ready"
- SPARC Architecture Version 8: 100% binary compatible